## 2SC2497, 2SC2497A

## Silicon NPN epitaxial planar type

For low-frequency power amplification
Complementary to 2SA1096, 2SC1096A

Features

- High collector-emitter voltage (Base open) $\mathrm{V}_{\mathrm{CEO}}$
- TO-126B package which requires no insulation plate for installation to the heat sink

Absolute Maximum Ratings $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$

| Parameter |  | Symbol | Rating | Unit |
| :--- | :---: | :---: | :---: | :---: |
| Collector-base voltage (Emitter open) | $\mathrm{V}_{\mathrm{CBO}}$ | 70 | V |  |
| Collector-emitter voltage <br> (Base open) | 2SC2497 | $\mathrm{V}_{\mathrm{CEO}}$ | 50 | V |
|  | 2SC2497A |  | 60 |  |
| Emitter-base voltage (Collector open) | $\mathrm{V}_{\text {EBO }}$ | 5 | V |  |
| Collector current | $\mathrm{I}_{\mathrm{C}}$ | 1.5 | A |  |
| Peak collector current | $\mathrm{I}_{\mathrm{CP}}$ | 3 | A |  |
| Collector power dissipation | $\mathrm{P}_{\mathrm{C}}$ | 1.2 | W |  |
| Junction temperature | $\mathrm{T}_{\mathrm{j}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage temperature | $\mathrm{T}_{\text {stg }}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |  |



Electrical Characteristics $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C} \pm 3^{\circ} \mathrm{C}$

| Parameter |  | Symbol | Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Collector-base voltage (Emitter open) |  | $\mathrm{V}_{\text {Cbo }}$ | $\mathrm{I}_{\mathrm{C}}=1 \mathrm{~mA}, \mathrm{I}_{\mathrm{E}}=0$ | 70 |  |  | V |
| Collector-emitter voltage (Base open) | 2SC2497 | $\mathrm{V}_{\text {CEO }}$ | $\mathrm{I}_{\mathrm{C}}=2 \mathrm{~mA}, \mathrm{I}_{\mathrm{B}}=0$ | 50 |  |  | V |
|  | 2SC2497A |  |  | 60 |  |  |  |
| Collector-base cutoff current (Emitter open) |  | $\mathrm{I}_{\text {CBO }}$ | $\mathrm{V}_{\mathrm{CB}}=20 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=0$ |  |  | 1 | $\mu \mathrm{A}$ |
| Collector-emitter cutoff current (Base open) |  | $\mathrm{I}_{\text {CEO }}$ | $\mathrm{V}_{\mathrm{CE}}=10 \mathrm{~V}, \mathrm{I}_{\mathrm{B}}=0$ |  |  | 100 | $\mu \mathrm{A}$ |
| Emitter-base cutoff current (Collector open) |  | $\mathrm{I}_{\text {Ebo }}$ | $\mathrm{V}_{\mathrm{EB}}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=0$ |  |  | 10 | $\mu \mathrm{A}$ |
| Forward current transfer ratio *1,2 |  | $\mathrm{h}_{\text {FE }}$ | $\mathrm{V}_{\mathrm{CE}}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=1 \mathrm{~A}$ | 80 |  | 220 | - |
| Collector-emitter saturation voltage |  | $\mathrm{V}_{\mathrm{CE} \text { (sat) }}$ | $\mathrm{I}_{\mathrm{C}}=1.5 \mathrm{~A}, \mathrm{I}_{\mathrm{B}}=0.15 \mathrm{~A}$ |  |  | 1 | V |
| Base-emitter saturation voltage |  | $\mathrm{V}_{\text {BE(sat) }}$ | $\mathrm{I}_{\mathrm{C}}=1.5 \mathrm{~A}, \mathrm{I}_{\mathrm{B}}=0.15 \mathrm{~A}$ |  |  | 1.5 | V |
| Transition frequency |  | $\mathrm{f}_{\mathrm{T}}$ | $\mathrm{V}_{\mathrm{CB}}=5 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=-0.5 \mathrm{~A}, \mathrm{f}=200 \mathrm{MHz}$ |  | 150 |  | MHz |
| Collector output capacitance (Common base, input open circuited) |  | $\mathrm{C}_{\text {ob }}$ | $\mathrm{V}_{\mathrm{CB}}=20 \mathrm{~V}, \mathrm{I}_{\mathrm{E}}=0, \mathrm{f}=1 \mathrm{MHz}$ |  | 35 |  | pF |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *1: Pulse measurement
*2: Rank classification

| Rank | Q | R |
| :---: | :---: | :---: |
| $\mathrm{h}_{\mathrm{FE}}$ | 80 to 160 | 120 to 220 |




$\mathrm{h}_{\mathrm{FE}}-\mathrm{I}_{\mathrm{C}}$

$\mathrm{V}_{\mathrm{CER}}-\mathrm{R}_{\mathrm{BE}}$






Safe operation area


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